



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit 2815

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Linda H. Liu, Reg. No. 51,240

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United States Patent and Trademark Office
P.O. Box 2327
Arlington, VA 22202

Dear Sir:

In response to the Office Action mailed July 5, 2002, please amend the above captioned application as follows:

Please amend the drawings to conform to the drawings provided by the SUBMISSION OF PROPOSED DRAWING AMENDMENT FOR APPROVAL BY EXAMINER documented submitted concurrently herewith.

IN THE CLAIMS

Please amend the claims as follows:

1. (Amended) A high density semiconductor structure having a plurality of integrated circuit chips, comprising:
- a first integrated circuit chip having an upper bonding surface;